

AMPMODU | AMPMODU Headers

TE Internal #: 826467-8

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.

1 in] Centerline, Partially Shrouded, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 1

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	8
Number of Rows	1
Board-to-Board Configuration	Parallel

Electrical Characteristics

Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms

Body Features

Connector Profile	Standard
Primary Product Color	Black

Contact Features

PCB Contact Termination Area Plating Material Thickness	3 µm
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Contact Shape & Form Round Contact Underplating Material Nickel PCB Contact Termination Area Plating Material I'm Contact Base Material Copper Zinc, Phosphor Bronze Contact Mating Area Plating Material Gold Flosh over Palladium Nickel Contact Mating Area Plating Material Thickness & # pm[31.5 pin] Contact Type Pin Contact Current Rating (Max) 3 A Termination Features Round Termination Post & Tall Diameter & # # # # # # # # # # # # # # # # # #	Mating Pin Diameter	.63 mm[.025 in]
PCB Contact Termination Area Plating Material Contact Rase Material Contact Mating Area Plating Material Thickness .9 µm(31.5 µin) Contact Type Pin Contact Current Rating (Max) 3 A Termination Features Round Termination Post 8-Tail Diameter Jermination Post 8-Tail Length Termination Post 8-Tail Length Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Retention Mating Retention Iype Detent Larching Mating Alignment With Mating Alignment Type Polarization PCB Mount Retention PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerins (Pitch) Losing Features Centerins (Pitch) Losing Material Polyester-Cit Dimensions Row-to-Row Specing PCB Thickness (Recommended) Usage Conditions Housing Lemperature Rating High Operating Lemperature Range JSS – 105 *CL-67 – 221 *F.] Operation/Application	Contact Shape & Form	Round
Contact Base Material Copper Zinc, Phosphor Bronze Contact Mating Area Plating Material Cold Flash over Pallacium Nickel Contact Mating Area Plating Material Thickness 8, µm(31.5 µm) Contact Type Pin Contact Current Rating (Max) 3 A Termination Features Round Termination Post & Tail Diameter 63 mm(,025 in) Termination Post & Tail Diameter 7, 22 mm(,126 in) Termination Method to Printed Circuit Board 7, 2 mm(,126 in) Termination Method to Printed Circuit Board 7, 2 mm(,126 in) Termination Method to Printed Circuit Board 8, 3 mm(,126 in) Mating Retention 8, 3 mm(,126 in) Mating Retention 9, 2 mm(,126 in) Mating Alignment 1, 3 mm(,126 in) Mating Alignment 1, 3 mm(,126 in) PCB Mount Retention 9, 3 mm(,126 in) PCB Mount Retention 9, 3 mm(,126 in) PCB Mount Alignment 9, 2 mm(,126 in) Mating Features Centerine (Pitch) 2, 2, 4 mm(,126 in) Housing Material 9, 2, 5 mm(,126 in) PCB Thickness (Recommended) 1, 5 mm(,062 in) Usage Conditions Housing Temperature Rating High Operation/Application	Contact Underplating Material	Nickel
Contact Mating Area Plating Material Gold Flash over Palladium Nickel Contact Mating Area Plating Material Thickness & & µm(31.5 µin) Contact Type Pln Contact Current Rating (Max) 3 A Termination Features Round Termination Post & Tail Diameter	PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	Contact Base Material	Copper Zinc, Phosphor Bronze
Contact Type Contact Current Rating (Max) Termination Features Round Termination Post & Tail Diameter .63 mml, 025 in] Termination Post & Tail Length .3.2 mml, 126 in] Termination Method to Printed Circuit Board Through Hole Solder Mechanical Attachment Mating Retention With Mating Retention Type Detent Latching Mating Alignment Meting Alignment Type Polarization PCB Mount Retention Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 1.57 mml, 157 mml, 062 in] Usage Conditions Housing Temperature Rating Operation/Application High Operation/Application	Contact Mating Area Plating Material	Gold Flash over Palladium Nickel
Contact Current Rating (Max) Termination Features Round Termination Post & Tail Length Termination Method to Printed Circuit Board Mechanical Attachment Mating Retention Mating Retention Type Detent Latching Mating Alignment With Mating Alignment Iype Polarization PCB Mount Retention Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Loss Amn (1 in) Housing Material Polyester GF Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operation/Application	Contact Mating Area Plating Material Thickness	.8 μm[31.5 μin]
Termination Features Round Termination Post & Tail Diameter .63 mml, 025 in Termination Post & Tail Length .3.2 mml, 126 in Termination Method to Printed Circuit Board .Through Hole - Solder	Contact Type	Pin
Round Termination Post & Tail Diameter .63 mm[.025 in] Termination Post & Tail Length 3.2 mm[.126 in] Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Retention With Mating Retention Type Detent Latching Mating Alignment With Mating Alignment Type Polarization PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Polyester-GF Dimensions Row-to-Row Spacing 2.54 mm[.1 in] PCB Thickness (Recommended) 1.57 mm[.062 in] Usage Conditions Housing Temperature Rating High Operation/Application	Contact Current Rating (Max)	3 A
Termination Post & Tail Length Termination Method to Printed Circuit Board Through Hole - Solder Mechanical Attachment Mating Retention Mating Retention Type Detent Latching Mating Alignment Mating Alignment Mating Alignment Type Polarization PCB Mount Retention PCB Mount Retention Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Louing Material Polyester-GF Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operation/Application	Termination Features	
Termination Method to Printed Circuit Board Mechanical Attachment Mating Retention Mating Retention Type Detent Latching Mating Alignment Mating Alignment Type Polarization PCB Mount Retention Without PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Lousing Material Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operation/Application	Round Termination Post & Tail Diameter	.63 mm[.025 in]
Mechanical Attachment Mating Retention With Mating Retention Type Detent Latching Mating Alignment With Mating Alignment Type Polarization PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Centerline (Pitch) 2.54 mm[.1 in] Housing Material Polyester-GF Dimensions Row-to-Row Spacing Row-to-Row Spacing 2.54 mm[.1 in] PCB Thickness (Recommended) 1.57 mm[.062 in] Usage Conditions Housing Temperature Rating High Operation/Application -55 – 105 °C[-67 – 221 °F]	Termination Post & Tail Length	3.2 mm[.126 in]
Mating Retention Type Detent Latching Mating Alignment With Mating Alignment Type Polarization PCB Mount Retention Without PCB Mount Alignment Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 2.54 mm[.1 in] Housing Material Polyester-GF Dimensions Row-to-Row Spacing 2.54 mm[.1 in] PCB Thickness (Recommended) 1.57 mm[.062 in] Usage Conditions Housing Temperature Rating High Operation/Application	Termination Method to Printed Circuit Board	Through Hole - Solder
Mating Retention Type Mating Alignment With Mating Alignment Type Polarization PCB Mount Retention Without Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Louing Material Polyester-GF Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operation/Application Detent Latching With With With Polarization Without 2.54 mm[.1 in] Polyester-GF Lift Migh Dimensions High Operation/Application	Mechanical Attachment	
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PCB Mount Retention PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Lousing Material Polyester-GF Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Without Without Without Without Without Sometimes Board Mount 2.54 mm[.1 in] Polyester-GF Usage Conditions High Operation Temperature Rating Operation/Application	Mating Alignment	With
PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Lousing Material Polyester-GF Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application	Mating Alignment Type	Polarization
Connector Mounting Type Housing Features Centerline (Pitch) Housing Material Polyester-GF Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application Board Mount 2.54 mm[.1 in] Polyester-GF Dimensions High -55 – 105 °C[-67 – 221 °F] Operation/Application	PCB Mount Retention	Without
Housing Features Centerline (Pitch) Lousing Material Polyester-GF Dimensions Row-to-Row Spacing PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application	PCB Mount Alignment	Without
Centerline (Pitch) Housing Material Polyester-GF Dimensions Row-to-Row Spacing 2.54 mm[.1 in] PCB Thickness (Recommended) 1.57 mm[.062 in] Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application	Connector Mounting Type	Board Mount
Housing Material Polyester-GF Dimensions Row-to-Row Spacing 2.54 mm[.1 in] PCB Thickness (Recommended) 1.57 mm[.062 in] Usage Conditions Housing Temperature Rating High Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application	Housing Features	
Dimensions Row-to-Row Spacing 2.54 mm[.1 in] PCB Thickness (Recommended) 1.57 mm[.062 in] Usage Conditions Housing Temperature Rating High Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application	Centerline (Pitch)	2.54 mm[.1 in]
Row-to-Row Spacing 2.54 mm[.1 in] PCB Thickness (Recommended) 1.57 mm[.062 in] Usage Conditions Housing Temperature Rating Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application	Housing Material	Polyester-GF
PCB Thickness (Recommended) Usage Conditions Housing Temperature Rating Operating Temperature Range Operation/Application 1.57 mm[.062 in] High -55 – 105 °C[-67 – 221 °F]	Dimensions	
Usage Conditions Housing Temperature Rating Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application	Row-to-Row Spacing	2.54 mm[.1 in]
Housing Temperature Rating Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application	PCB Thickness (Recommended)	1.57 mm[.062 in]
Operating Temperature Range -55 – 105 °C[-67 – 221 °F] Operation/Application	Usage Conditions	
Operation/Application	Housing Temperature Rating	High
	Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Solder Process Feature Board Standoff	Operation/Application	
	Solder Process Feature	Board Standoff



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Circuit Application	Signal
on eart / appreation	3191101

Industry Standards

Agency/Standard	CSA
Approved Standards	CSA LR7189, CUL E28476
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	150
Packaging Type	Carton

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | AMPMODU Headers



PCB Connector Mounting(1)



PCB Connector Shrouds(1)



PCB Headers & Receptacles(4872)



PCB Latches, Locks & Retainers(1)



Wire-to-Board Connector Assemblies & Housings(5)



Wire-to-Board Connector Contacts(65)

Customers Also Bought



TE Part #5747842-4
25 MSFL PLUG RA 318 (IN,FM,BL)



TE Part #9-966140-1 AMP MCP Unsealed Headers



TE Part #1393774-8 V23026A1002B201

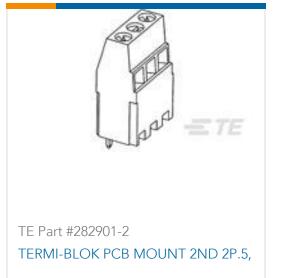




TE Part #4-794630-8 18P MICRO MNL ASSY,VRT,HDR,LF



TE Part #966870-1 MOD2 ST-WANNE 2X 8P









Documents

Product Drawings

8P MOD II SHROUDED HEADER, ST

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_826467-8_F.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_826467-8_F.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_826467-8_F.3d_stp.zip

English

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Product Environmental Compliance

Product Compliance

English

Product Compliance

English

Agency Approvals

UL Report

English